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MIRTEC Receives GLOBAL Technology Award for MV-9 SiP HYBRID 3D AOI

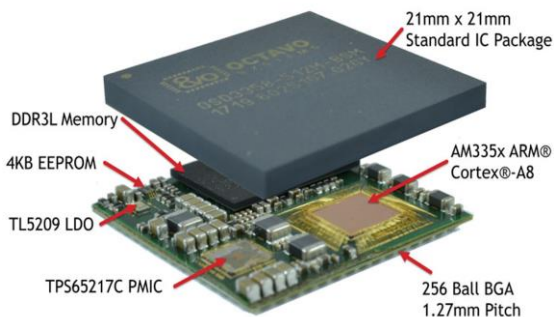
November 2021 – MIRTEC, 'The Global Leader in Inspection Technology,' is pleased to announce that it received a 2021 GLOBAL Technology Award in the category of Inspection – AOI systems for its MV-9 SiP HYBRID 3D AOI system. The award was announced during a ceremony that took place Tuesday, Nov. 16, 2021 during productronica in Munich, Germany.

The all new MV-9 SiP HYBRID 3D AOI system combines MIRTEC's exclusive OMNI-VISION® 3D Inspection Technology with a High-Resolution Laser System for precision 3D Inspection of System-In-Package (SiP) applications. This powerful new system is configured with MIRTEC's exclusive 25 Mega Pixel CoaXPRESS Camera and 12 Projection Digital Tri-Frequency Moiré 3D Technology. MIRTEC's 25 Mega Pixel CoaXPRESS Camera is a proprietary Industrial Camera designed and manufactured by MIRTEC for use with the complete product range of inspection equipment.

MIRTEC's Digital Tri-Frequency Technology provides FULL 3D PCB inspection using a total of 12 Projected 3D Frequencies for precise height measurement used to detect lifted component and lifted lead defects as well as solder volume post reflow. The High-Resolution 3D Laser is primarily used to inspect devices with highly reflective and highly absorbent surface characteristics.



SiP Assembly Technology presents a host of challenges to the inspection environment including PCB density and diversity of SMT device materials. MIRTEC's MV-9 SiP 3D AOI machine was specifically developed to address these challenges. MIRTEC's HYBRID Inspection Technology combines its Award-Winning OMNI-VISION® 3D Inspection System with a High-Resolution Laser to provide PRECISION 3D inspection of SMT devices on finished PCB assemblies regardless of surface characteristics. This proprietary system yields precise height measurement used to detect lifted component and lifted lead defects as well as solder volume post reflow.





Fully configured the new MIRTEC MV-9 SiP 3D AOI machines feature four (4) 18 Mega Pixel Side-View Cameras in addition to the 25 Mega Pixel Top-Down CoaXPress Camera. There is little doubt that this new technology will set the standard by which all other inspection equipment will be measured.

The GLOBAL Technology Awards have recognized the very best new innovations in the printed circuit assembly and packaging industries since 2005. The prestigious awards contest has been bringing together the global SMT and advanced packaging industry in a celebration of the companies and people that are achieving the highest standards and driving our industry forward. For more information, visit www.globalsmt.net/awards.

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MIRTEC is a Leading Global Supplier of Automated Inspection Systems to the Electronics Manufacturing Industry. For further information, please visit www.mirtecusa.com

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